Protecting a brand is becoming more and more difficult.

In today's market, counterfeit could create serious damage to the brand and reputation, more particularly in high-value or luxurious products. The end-customers trust their preferred Brands in the authenticity and integrity of the products they purchase. Brands therefore need to ensure that each product they deliver is genuine.

Linxens has developed the EcoBrand product range to ensure the authenticity of products. With its minimal size, the innovative EcoBrand connector can be inserted within the product's smallest possible space, allowing to connect the Secure Chip which will determine the product's authenticity.

To make this happen, the R&D of Linxens has selected the thinnest base material of 75µm Epoxy Glass and only 18µm copper which allow us to obtain a module thickness of 350µm maximum, and thus easing the integration of the connector in the end-product.

Key Features
- Thinnest total thickness manufacture
- 3-pad connector suitable for SWI (Single Wire Protocol) secure chip
- Robust plating protection to support 500 insertions in the connector

Typical Product Design

<table>
<thead>
<tr>
<th>Part number</th>
<th>Dimension</th>
<th>Up per 35mm width</th>
<th>Max Chip Dimension</th>
<th>Number of connection</th>
<th>Total module thickness</th>
</tr>
</thead>
<tbody>
<tr>
<td>9X65101</td>
<td>2.6 x 3.0 mm</td>
<td>6</td>
<td>1.2 x 1.2 mm</td>
<td>3 pads</td>
<td>350µm</td>
</tr>
</tbody>
</table>

Linxens offers chip module assembly on EcoBrand, for further information please see the Module Packaging Services datasheet.

To meet specific requirements, feel free to contact Linxens for any requests of tailor-made solutions.